


DMV1500SD

DAMPER + MODULATION DIODE FOR VIDEO

Table 1: Main Product Characteristics

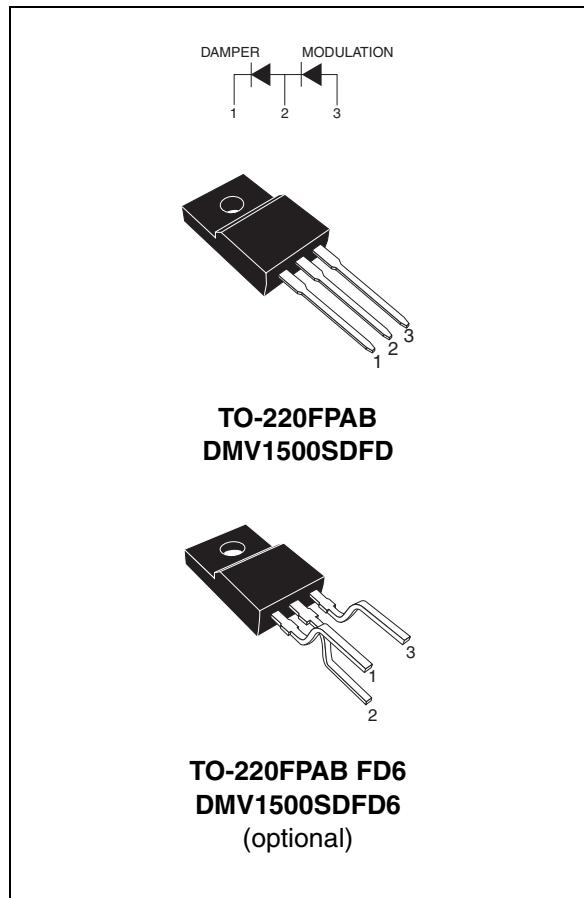
| | DAMPER | MODUL. |
|-----------------------|--------|--------|
| I _{F(AV)} | 6 A | 6 A |
| V _{RRM} | 1500 V | 600 V |
| t _{rr} (typ) | 150 ns | 60 ns |
| V _F (typ) | 1.1 V | 1.0 V |

FEATURES AND BENEFITS

- Full kit in one package
- High breakdown voltage capability
- Very fast recovery diode
- Specified turn on switching characteristics
- Low static and peak forward voltage drop for low dissipation
- Insulated version:
- Insulated voltage = 2000 V_{RMS}
- Capacitance = 7 pF
- Planar technology allowing high quality and best electrical characteristics
- Outstanding performance of well proven DTV as damper and new faster Turbo 2 600V technology as modulation

DESCRIPTION

High voltage semiconductor especially designed for horizontal deflection stage in standard and high resolution video display with E/W correction. The insulated TO-220FPAB package includes both the DAMPER diode and the MODULATION diode, thanks to a dedicated design. Assembled on automated line, it offers very low dispersion values on insulating and thermal performances.


Table 2: Order Codes

| Part Number | Marking |
|--------------|-----------|
| DMV1500SDFD | DMV1500SD |
| DMV1500SDFD6 | DMV1500SD |

DMV1500SD**Table 3: Absolute Ratings** (limiting values, per diode)

| Symbol | Parameter | Value | | Unit |
|------------------|--|-------------|--------|------|
| | | Damper | Modul. | |
| V _{RRM} | Repetitive peak reverse voltage | 1500 | 600 | V |
| I _{FSM} | Surge non repetitive forward current tp = 10ms sinusoidal | 50 | 50 | A |
| T _{stg} | Storage temperature range | -40 to +150 | | °C |
| T _j | Maximum operating junction temperature | 150 | | °C |

Table 4: Thermal resistances

| Symbol | Parameter | Value (max.) | Unit |
|----------------------|-------------------------------------|--------------|------|
| R _{th(j-c)} | Junction to case thermal resistance | 4 | °C/W |

Table 5: Static Electrical Characteristics

| Symbol | Parameter | Test conditions | Value | | | | Unit | |
|-------------------|-------------------------|-----------------|-------------------------|------|------------------------|------|------|----|
| | | | T _j = 25°C | | T _j = 125°C | | | |
| | | | Typ. | Max. | Typ. | Max. | | |
| I _R * | Reverse leakage current | Damper | V _R = 1500 V | | 100 | 100 | 1000 | µA |
| | | Modul. | V _R = 600 V | | 3 | 3 | 30 | |
| V _F ** | Forward voltage drop | Damper | I _F = 6 A | 1.2 | 1.75 | 1.1 | 1.5 | V |
| | | Modul. | I _F = 6 A | 1.15 | 1.4 | 1 | 1.25 | |

Pulse test: * tp = 5 ms, δ < 2%

** tp = 380 µs, δ < 2%

To evaluate the maximum conduction losses of the **DAMPER** and **MODULATION** diodes use the following equations :

DAMPER: P = 1.2 × I_{F(AV)} + 0.050 × I_F²(RMS)

MODULATION: P = 0.89 × I_{F(AV)} + 0.055 × I_F²(RMS)

Table 6: Recovery Characteristics

| Symbol | Parameter | Test conditions | Value | | | | Unit | |
|-----------------|-----------------------|--|-----------------------|------|--------|------|------|----|
| | | | Damper | | Modul. | | | |
| | | | Typ. | Max. | Typ. | Max. | | |
| t _{rr} | Reverse recovery time | I _F = 100mA I _R =100mA I _{RR} = 10mA | T _j = 25°C | 1000 | 2000 | 250 | 400 | ns |
| | | I _F = 1A dI _F /dt = -50 A/µs V _R =30V | T _j = 25°C | 150 | 250 | 60 | 85 | |

Table 7: Turn-On Switching Characteristics

| Symbol | Parameter | Test conditions | | | Value | | Unit |
|----------|-----------------------|-----------------|---|---------------------------|-------|------|------|
| | | | Typ. | Max. | Typ. | Max. | |
| t_{fr} | Forward recovery time | Damper | $I_F = 6 \text{ A}$ $dI_F/dt = 80 \text{ A}/\mu\text{s}$ $V_{FR} = 3 \text{ V}$ | $T_j = 100^\circ\text{C}$ | 350 | 500 | ns |
| | | Modul. | $I_F = 6 \text{ A}$ $dI_F/dt = 80 \text{ A}/\mu\text{s}$ $V_{FR} = 2 \text{ V}$ | $T_j = 100^\circ\text{C}$ | 70 | 125 | |
| V_{FP} | Peak forward voltage | Damper | $I_F = 6 \text{ A}$ $dI_F/dt = 80 \text{ A}/\mu\text{s}$ | $T_j = 100^\circ\text{C}$ | 26 | 36 | V |
| | | Modul. | $I_F = 6 \text{ A}$ $dI_F/dt = 80 \text{ A}/\mu\text{s}$ | $T_j = 100^\circ\text{C}$ | 5 | 7.5 | |

Figure 1: Power dissipation versus peak forward current (triangular waveform, $\delta=0.45$) (damper diode)

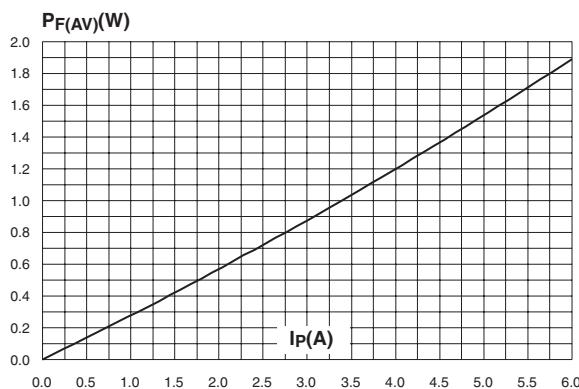


Figure 2: Power dissipation versus peak forward current (triangular waveform, $\delta=0.45$) (modulation diode)

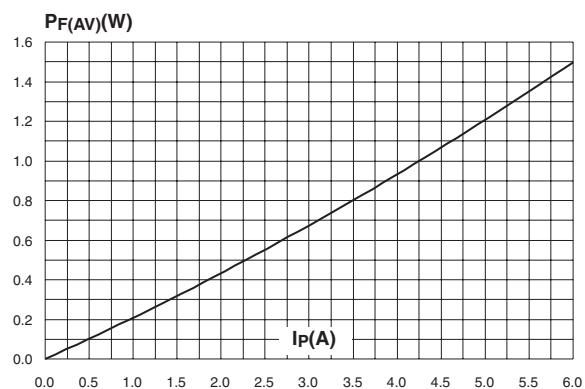


Figure 3: Average forward current versus ambient temperature

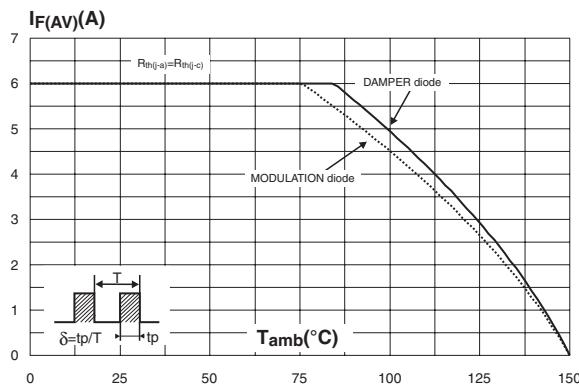
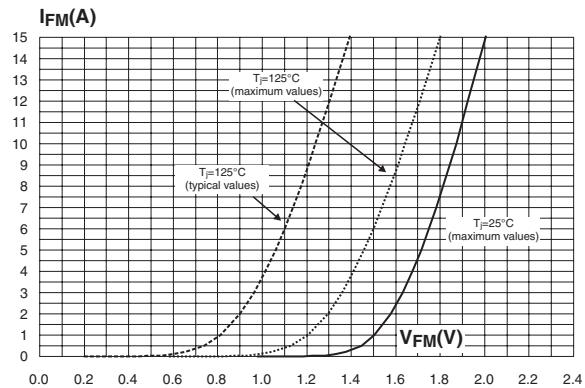


Figure 4: Forward voltage drop versus forward current (damper diode)



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Figure 5: Forward voltage drop versus forward current (modulation diode)

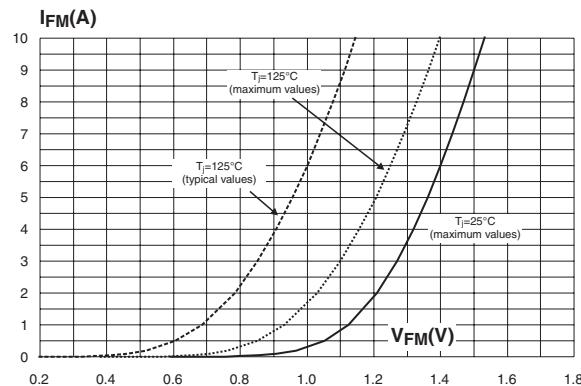


Figure 6: Relative variation of thermal impedance junction to case versus pulse duration

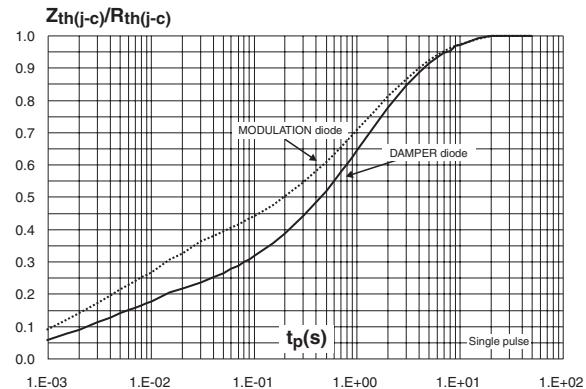


Figure 7: Reverse recovery charges versus dI_F/dt (damper diode)

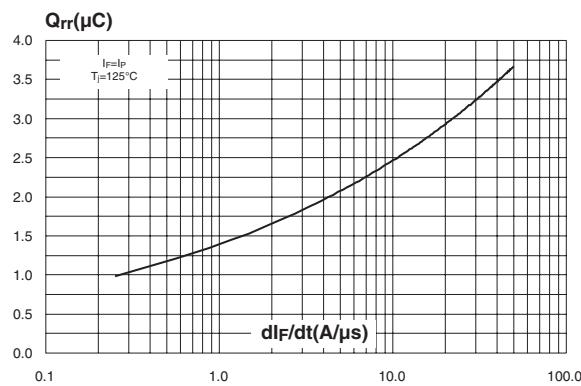


Figure 8: Reverse recovery charges versus dI_F/dt (modulation diode)

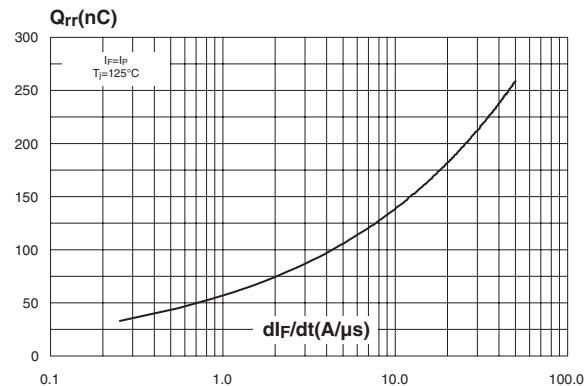


Figure 9: Peak reverse recovery current versus dI_F/dt (damper diode)

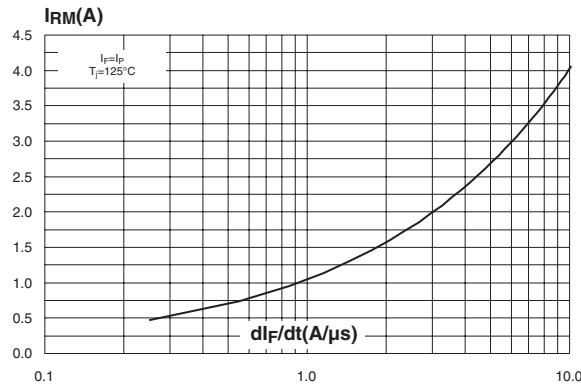


Figure 10: Peak reverse recovery current versus dI_F/dt (modulation diode)

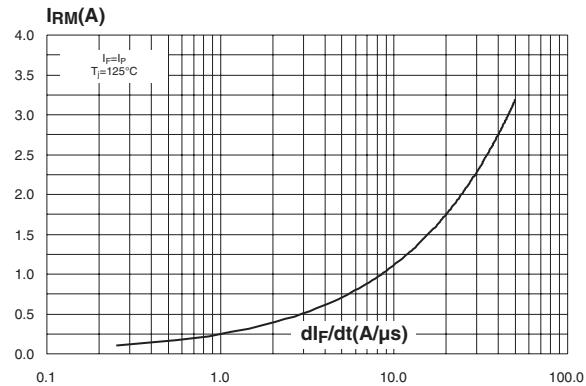


Figure 11: Transient peak forward voltage versus dI_F/dt (damper diode, typical values)

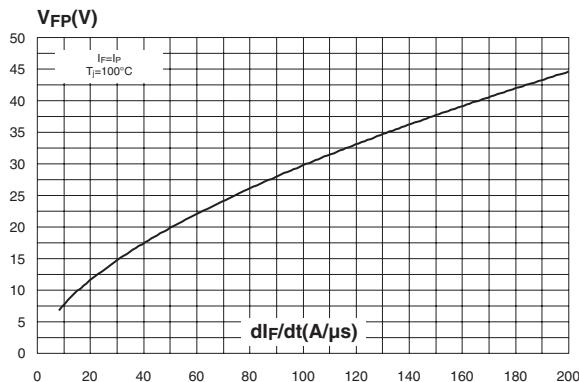


Figure 13: Forward recovery time versus dI_F/dt (damper diode, typical values)

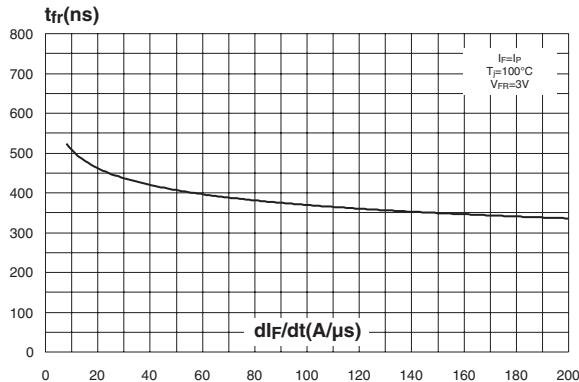


Figure 15: Relative variation of dynamic parameters versus junction temperature

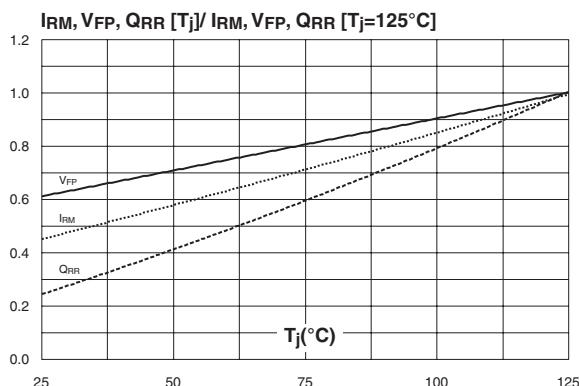


Figure 12: Transient peak forward voltage versus dI_F/dt (modulation diode, typical values)

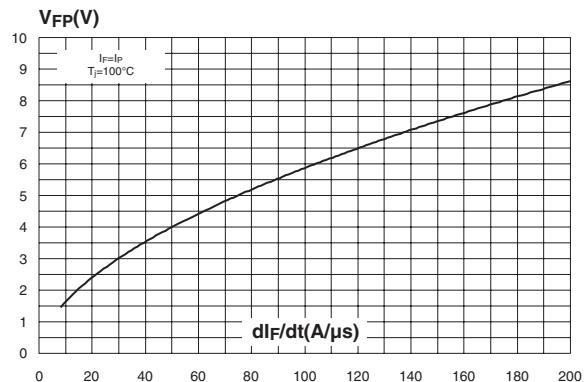


Figure 14: Forward recovery time versus dI_F/dt (modulation diode, typical values)

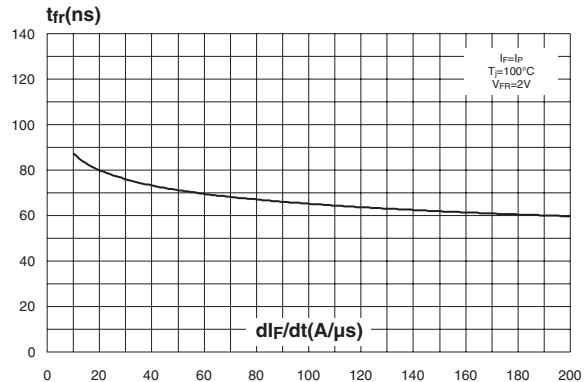
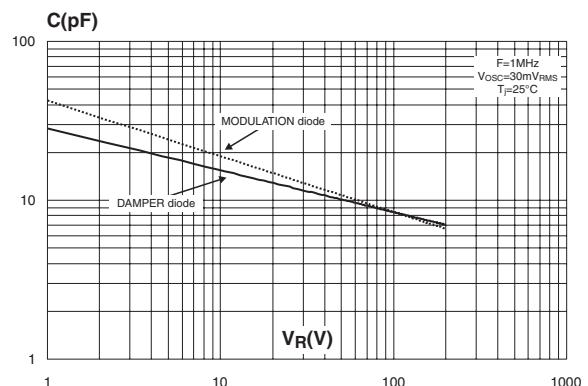
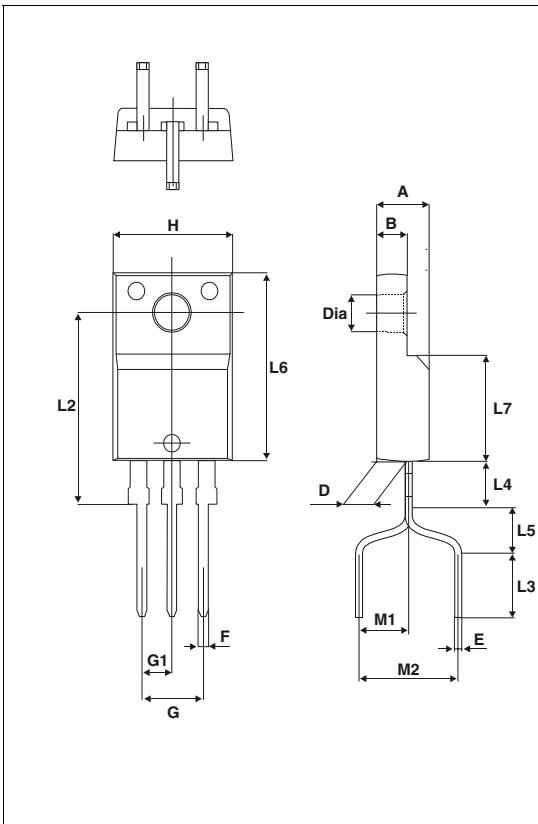


Figure 16: Junction capacitance versus reverse voltage applied (typical values)



DMV1500SD**Figure 17: TO-220FPAB FD6 Option Package Mechanical Data**


| REF. | DIMENSIONS | | | |
|------|-------------|------|------------|-------|
| | Millimeters | | Inches | |
| | Min. | Max. | Min. | Max. |
| A | 4.4 | 4.9 | 0.173 | 0.192 |
| B | 2.5 | 2.9 | 0.098 | 0.114 |
| D | 2.45 | 2.75 | 0.096 | 0.108 |
| E | 0.4 | 0.7 | 0.016 | 0.028 |
| F | 0.6 | 1 | 0.024 | 0.039 |
| G | 4.95 | 5.2 | 0.195 | 0.205 |
| G1 | 2.4 | 2.7 | 0.094 | 0.106 |
| H | 10 | 10.7 | 0.394 | 0.421 |
| L2 | 12.7 | 12.8 | 0.500 | 0.504 |
| L3 | 4.8 Typ. | | 0.189 Typ. | |
| L4 | 3.8 | 4.2 | 0.150 | 0.165 |
| L6 | 2.8 | 3.2 | 0.110 | 0.126 |
| L7 | 9 | 9.9 | 0.354 | 0.390 |
| M1 | 3.75 Typ. | | 0.148 Typ. | |
| M2 | 7 | 8 | 0.276 | 0.315 |
| R | 1 Typ. | | 0.039 Typ. | |
| Dia. | 2.9 | 3.5 | 0.114 | 0.138 |

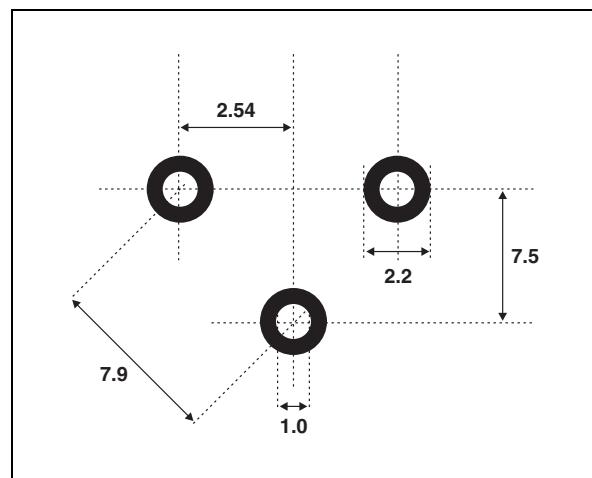
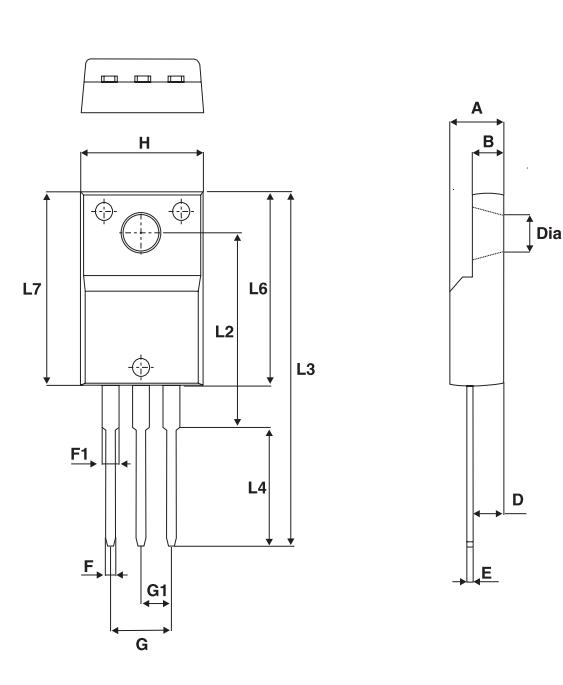
Figure 18: TO-220FPAB FD6 PCB layout
(typical, in millimeters)

Figure 19: TO-220FPAB Package Mechanical Data



| REF. | DIMENSIONS | | | |
|------|-------------|------|------------|-------|
| | Millimeters | | Inches | |
| | Min. | Max. | Min. | Max. |
| A | 4.4 | 4.9 | 0.173 | 0.192 |
| B | 2.5 | 2.9 | 0.098 | 0.114 |
| D | 2.45 | 2.75 | 0.096 | 0.108 |
| E | 0.4 | 0.7 | 0.016 | 0.027 |
| F | 0.6 | 1 | 0.024 | 0.039 |
| F1 | 1.15 | 1.7 | 0.045 | 0.067 |
| F2 | 1.15 | 1.7 | 0.045 | 0.067 |
| G | 4.95 | 5.2 | 0.195 | 0.205 |
| G1 | 2.4 | 2.7 | 0.094 | 0.106 |
| H | 10 | 10.7 | 0.393 | 0.421 |
| L2 | 16 Typ. | | 0.630 Typ. | |
| L3 | 28.6 | 30.6 | 1.126 | 1.205 |
| L4 | 9.8 | 10.7 | 0.385 | 0.421 |
| L6 | 15.8 | 16.4 | 0.622 | 0.646 |
| L7 | 9 | 9.9 | 0.354 | 0.390 |
| Dia. | 2.9 | 3.5 | 0.114 | 0.138 |

Table 8: Ordering Information

| Part Number | Marking | Package | Weight | Base qty | Delivery mode |
|--------------|-----------|----------------|--------|----------|---------------|
| DMV1500SDFD | DMV1500SD | TO-220FPAB | 2.4 g | 50 | Tube |
| DMV1500SDFD6 | DMV1500SD | TO-220FPAB FD6 | 2.4 g | 45 | Tube |

Table 9: Revision History

| Date | Revision | Description of Changes |
|-------------|----------|------------------------|
| 25-Oct-2004 | 1 | First issue |

DMV1500SD

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